



- 1.二次電鍍pin腳平整度公差≥0.10mm.
- 2.pin腳表面電鍍以霧面,亮面皆可.
- 3.高壓PIN腳埋入1.0m/m±0.10.
- 4.毛邊不得大於0.03m/m.

REV.	REVISIONS REC.	DATE	REV.	REVISIONS REC.	DATE
4	凸點底部增加圓角為R0.20	4/14/05	7	(J1):∅0.7±0.05->∅0.7+0.05/-0	2/08/06
5	凸點底部圓角改為以C角 5	6/01/05		(K1):0.56->0.80;(L1):0.50->0.80	
6	(G):24.0->24.0±0.1	1/13/06			

DRAWN & DRAFTED BY WANG GANG	TOLERANCES		ANGLE:	TITLE:		
	0<L≤4 ±0.05	COPLANARITY 0.1 MAX	±1°	SMD BOBBIN LH-10(10 SEC)		
4<L≤16 ±0.10	UNIT:		MM	BOBBIN MATERIAL: LCP E4008		UL REC. UL 94V-0
CHECKED & APPROVED BY			ORIGIN: SZ	PIN MATERIAL: PHOSPHOR BRONZE		PIN TENSION LOAD: 2.0KG MIN
PIN SHINE INDUSTRIAL CO., LTD. TEL:886-2-22990545 FAX:886-2-22990546			DATE: FEB.08 '2006	DRAWING NO. S-1011-4	REV. 7	